Product Change Notification / LIAL-23CCBP390

Date:

10-Feb-2022

Product Category:

AntiFuse FPGAs, General Purpose FPGAs, System On Chip FPGAs

PCN Type:

Manufacturing Change

Notification Subject:

eSign # E000089324 Final Notice: Qualification of ASEM as a new assembly site for selected Microsemi products available in 144L, 256L, and 324L LFBGA, 281L and 288L TFBGA packages.

Affected CPNs:

LIAL-23CCBP390_Affected_CPN_02102022.pdf
LIAL-23CCBP390_Affected_CPN_02102022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASEM as a new assembly site for selected Microsemi products available in 144L, 256L, and 324L LFBGA, 281L and 288L TFBGA packages.

Pre and Post Change Summary:

	Pre-Change	**Post Change**
Assembly Site	UTAC Dongguan Limited	ASE Group -Malaysia

	(UDG)		(ASEM)	
Wire material	Au	CuPd	Au	CuPdAu
	Refer to attached excel file for details of material change by device.			
Die attach material	CRM-1076WB	CRM1525D	2100A	
	Refer to attached excel file for details of material change by device.			
Molding compound material	KE-G1250LKDS-30		G750E	
	Refer to attached excel file for details of material change by device.			
Solder Ball	SAC305	SnPb	SAC305	SnPb
	Refer to attached excel file for details of material change by device.			

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve productivity by qualifying ASEM as a new assembly site.

Note: Because of capacity constraints that have been observed throughout the industry there may be limited or no inventory available as identified in the pre-change.

Change Implementation Status: In Progress

Estimated First Ship Date: February 28, 2022 (date code: 2210)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2021					**>**	**February 2022**				
Workweek	23	24	25	26	27		06	07	08	09	10
Initial PCN Issue Date				X							

Qual Report Availability								X			
Final PCN Issue Date								X			
Estimated Implementation Date											X

Method to Identify Change:1. Traceability code
2. Parts can be identified by Country of Origin marked on the unit. CHN (China) for devices built at UDG. MYS (Malaysia) for devices built at ASEM.

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:
June 25, 2021: Issued initial notification.
February 10, 2022: Issued final Notification under eSign# E000089324. Initial PCN was issued with reference Memo # ML062021004D & TRB# WW22. Attached the qualification report. Provided estimated first ship date to be on February 28, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-23CCBP390_Qual Report_PA-237_Au wire.pdf
PCN_LIAL-23CCBP390_Qual Report_PA-233_CuPdAu wire.pdf
PCN_LIAL-23CCBP390_Affected CPN_Cisco_with materials.pdf
PCN_LIAL-23CCBP390_Affected CPN_Cisco_with materials.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.